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METHOD OF PRODUCTION OF LEAD FRAME, LEAD FRAME, AND SEMICONDUCTOR DEVICE

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ABSTRACT OF THE DISCLOSURE

A method of production of a lead frame eliminating strain in the lead frame even if thinning the die pad by coining including a processing step of forming leads, a die pad, and a plurality of support bars formed integral with the die pad in a metal strip, a dividing step of dividing the die pad formed integrally with the support bars for each support bar so as to obtain a plurality of spaced apart pieces of the die pads, and a coining step of coining at least one main surface of each of the plurality of pieces of the die pad to thin the plurality of pieces of the die pad.

Fig. 1A